



IMC-5G

Suzhou, 2020

IEEE MTT-S International Microwave Conference on Hardware and Systems for 5G and Beyond

August 26th- 28th, 2020

Suzhou, China

CALL FOR PAPERS

CONFERENCE COMMITTEE

Conference General Chair:

Wei Hong, Southeast University, China

Conference General Co-Chairs:

Ke Wu, Polytechnique Montreal, Canada

Anding Zhu, Univ. College Dublin, Ireland

Technical Program Committee

Wenhua Chen (Chair), Tsinghua Univ., China

Chao Yu (Co-Chair), Southeast University, China

Nuno Borges Carvalho, Univ. of Aveiro, Portugal

Anding Zhu, Univ. College Dublin, Ireland

Maurizio Bozzi, Univ. of Pavia, Italy

Kaixue Ma, Tianjin Univ, China

Christian Fager, Chalmers, Sweden

Wei Hong, Southeast Univ., China

Tim Lee, Boeing, USA

Xiuyin Zhang, SCUT, China

Rui Ma, Mitsubishi Electric Research, USA

Abbas Omar, Univ. of Magdeburg, Germany

Jose Carlos Pedro, Univ. of Aveiro, Portugal

Gomez Garcia Roberto, Univ. of Alcala, Spain

Dominique Schreurs, KU Leuven, Belgium

Ke Wu, Polytechnique Montreal, Canada

Mohammad S. Sharawi, Polytechnique Montreal, Canada

Finance Chair

Xiaowei Zhu, Southeast University, China

Conference Secretary

Yao Lu, Nanjing Maitekang Conference Service Co. Ltd.

Contact:

Address: 9 East Mozhou Road, Nanjing 211111,
China

Email: yaolu@em-conf.com

Web: <http://imc-5G.mtt.org/>

SCOPE

5G and beyond, will have profound technological and economic impacts on our society. Many of the most difficult scientific challenges are located at the “Physical Layer”, due to some fundamental limitations imposed by the nature of electromagnetic energy used. As a result, significant research is required to enable advanced microelectronic circuits and smart hardware implementation to achieve a working system. The IMC-5G 2020 conference provides a unique opportunity to bring together researchers and practitioners of different background to share the most recent advances in hardware and system technologies for 5G.

IMC-5G 2020 will feature a two-day archival series of oral and poster presentations (in IEEE Xplore) with invited talks and tutorials. An industrial exhibit featuring a selection of state-of-the-art wireless and microwave products, measurement instruments and CAD software tools will also be held. The participation of young researchers and postgraduate students is strongly encouraged. Best Student Paper Awards will be made.

TOPICS

Technical contents include, but not limited to, the following areas:

- 5G RF/millimeter-wave transceiver architectures
- Highly integrated front-end modules and mixed-signal ICs
- Large-scale phased-array, beamformers, MIMO antennas
- High efficiency and broadband power amplifiers
- Signal generation, modulation and frequency conversion
- Reconfigurable circuit elements, filters, multiplexers
- IoT sensors, RFID circuits/chips for 5G applications
- RF/Microwave device, circuit and subsystem modelling
- OTA measurement, device/circuit characterization
- Energy harvesting, wireless power transfer circuits
- Nonlinear circuit/system analysis and simulation tools

IMPORTANT DATES

Abstract Submission Deadline:

April 16th, 2020

Notification of Acceptance:

June 30th, 2020

Final Manuscript Due:

July 20th, 2020

Conference Date:

August 26th-28th, 2020

SUBMISSIONS

Prospective authors are invited to submit a **three-page** extended abstract in PDF format before the Abstract Submission Deadline. All papers must be written in English, and submitted electronically from the conference website.

All submissions will be peer-reviewed. Authors of accepted contributions should provide a full-length (three-page) final version of their work before the Final Manuscript Submission Deadline. The final version of the paper will be published in the conference proceedings as well as submitted for inclusion in **IEEE Xplore Digital Library** provided it has been presented at the conference.

